

LIGHT EMITTING DIODE SPECIFICATION

CUSTOMER NAME:

DESCRIPTION: IE-3528Y-SB-BFO-E

REVISION: V2.2

ISSUE DATE: 2018 07 25

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Features:

- Long operating life
- Low Power Consumption
- Wide Viewing Angle
- Low voltage DC operated
- RoHS Compliant

Application:

- Backlight
- Decoration lighting
- motormeter
- Indicator

Part Number	Dice Material	Emitted Color	Lens Color
IE-3528Y-SB-BFO-E	InGaN	Yellow	Yellow Diffused

Electro Optical Characteristics (T_a=25°C, @20mA)

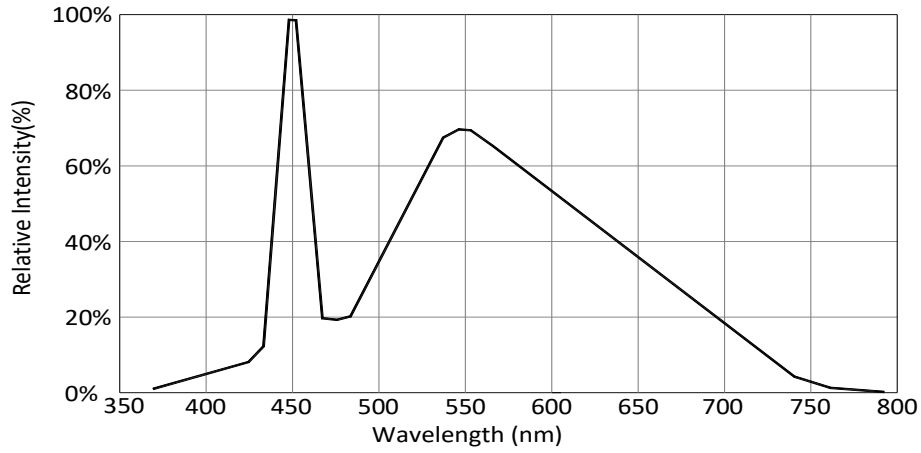
Parameter	Symbol	Min.	Typ.	Max.	Unit
Luminous Intensity	IV	1500	2000	2500	mcd
Radiation Bandwidth	$\Delta\lambda$				nm
Forward Voltage	V _F	2.90	3.00	3.40	v
Luminous Flux	Φ	5.0		7.0	Lm
Dominant Wavelength	λ_d	585	590	595	nm
CIE Coordinates CIE	x,y		0.56,0.42		
Color Temperature	CCT				k
Viewing Angle	2 θ 1/2		120		deg
Reverse Current	I _R			10	uA

Absolute Maximum Ratings (T_a=25°C)

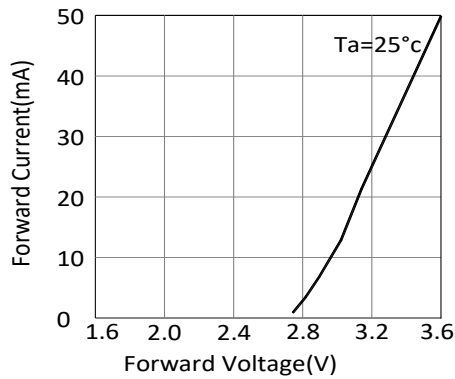
Parameter	Symbol	Max.	Unit
Peak Forward Current(1/10 Duty Cycle, 0.1ms Pulse Width)	I _{PF}	100	mA
Forward Current	I _F	30	mA
Reverse Voltage	V _R	5	v
Electrostatic Discharge	ESD	2000	v
Operating Temperature Range	T _{opr}	40to+90	°C
Storage Temperature Range	T _{stg}	40to+90	°C
Reflow Soldering	T _{sld}	260°C for 10secs	

Optical & Electrical Characteristics

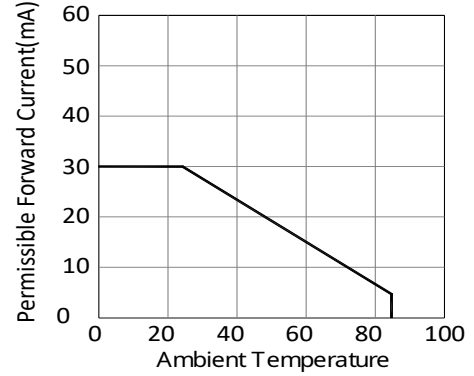
Spectrum



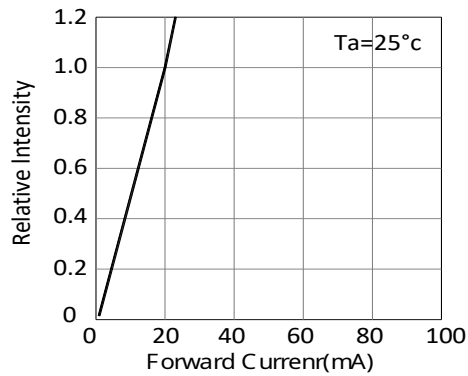
Forward Current vs. Forward Voltage



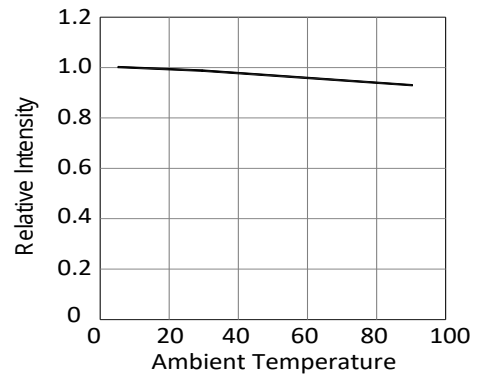
Forward Current vs. Ambient Temperature



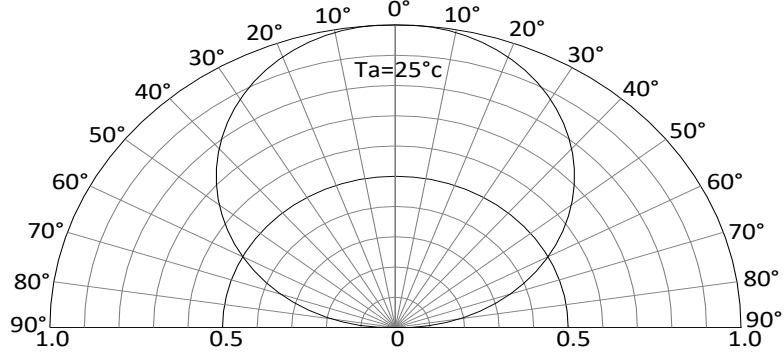
Relative Intensity vs. Forward Current



Relative Intensity vs. Ambient Temperature



Radiation Pattern



Bin Limits

Bin Range Of Luminous Intensity (Unit: mcd)

Bin Code	Min	Max	Condition
L1	1500	2000	IF=20mA
L2	2000	2500	
L3			
L4			

Bin Range Of Forward Voltage (Unit:V)

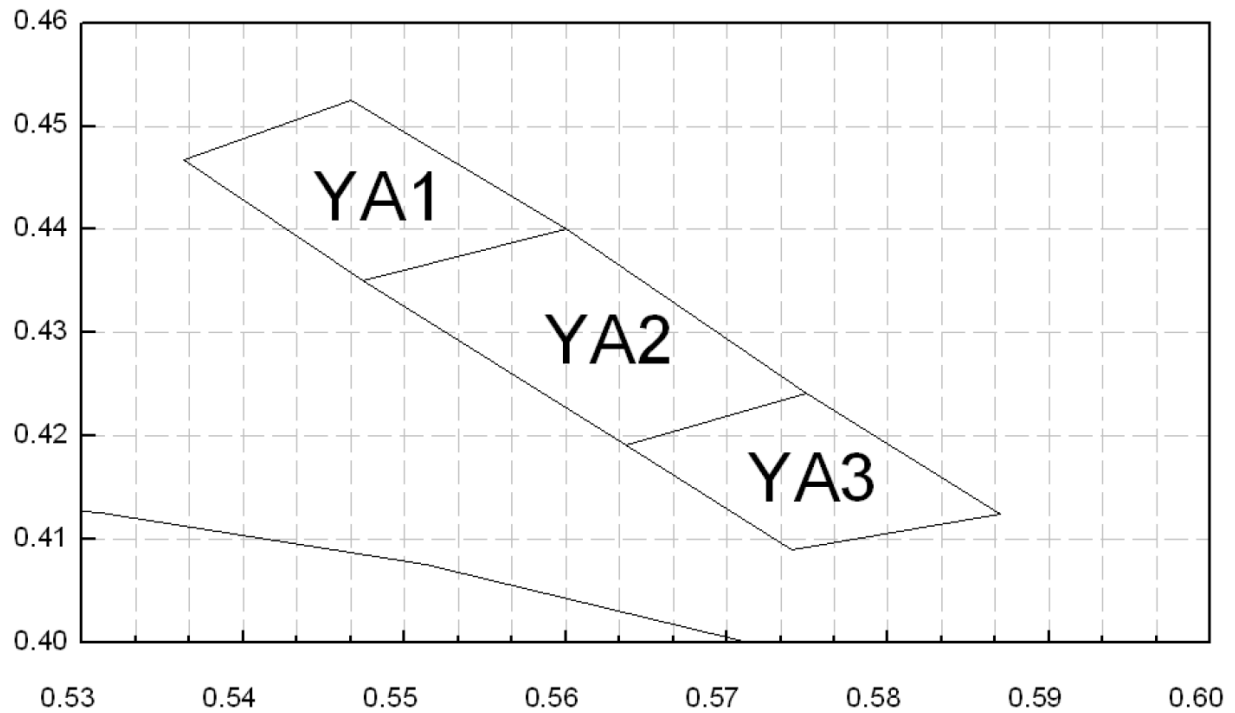
Bin Code	Min	Max	Condition
V1	2.8	2.9	IF=20mA
V2	2.9	3.0	
V3	3.0	3.1	
V4	3.1	3.2	
V5	3.2	3.3	

Notes:

1.Tolerance of Luminous Intensity $\pm 10\%$

2.Tolerance of Forward Voltage $\pm 0.1V$

CIE Chromaticity Diagram



Color Bin Limits

YA1		YA2		YA3	
CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y
0.5363	0.4467	0.5474	0.4351	0.5637	0.4191
0.5467	0.4525	0.5600	0.4400	0.5749	0.4242
0.5600	0.4400	0.5749	0.4242	0.5870	0.4124
0.5474	0.4351	0.5637	0.4191	0.5740	0.4090

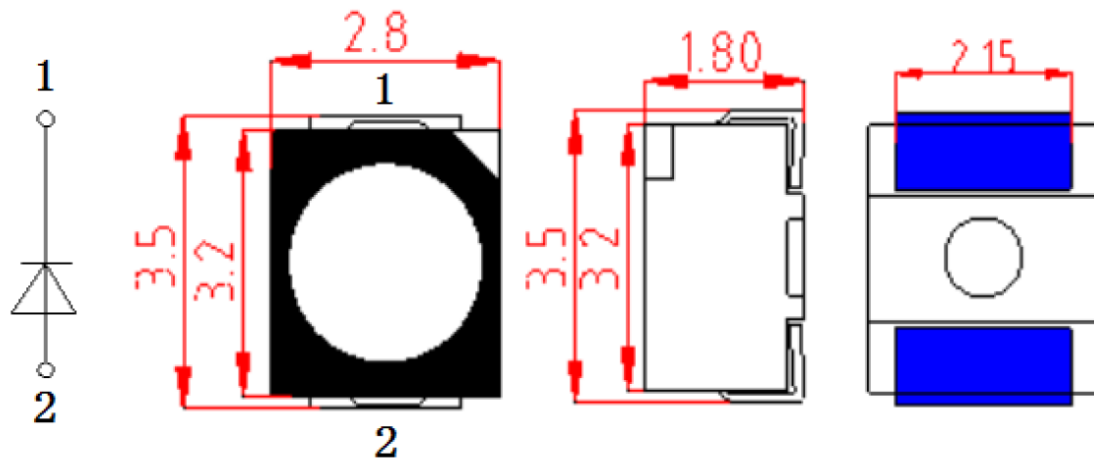
Reliability Test Items And Conditions

Test Items	Reference	Test Conditions	Time	Quantity	Criterion
Thermal Shock	MIL STD 202G	40°C (30min) 100°C (30min)	100 Cycles	22	0/22
Temperature And Humidity Cyclic	JEITA ED 4701 200 203	10°C~65°C; 0%~90%RH	10cycles	22	0/22
High Temperature Storage	JEITA ED 4071 200 201	Ta=100°C	1000H	22	0/22
Low Temperature Storage	JEITA ED 4071 200 202	Ta= 40°C	1000H	22	0/22
High Temperature High Humidity Storage	JEITA ED 4071 100 103	Ta=60°C; RH=90%	1000H	22	0/22
High Temperature Life Test	JESD22 A108D	Ta=80°C	1000H	22	0/22
Life Test	JESD22 A108D	Ta=25°C IF=20mA	1000H	22	0/22
Resistance to Sodering Heat	GB/T 4937, II , 2.2&2.3	Tsol*=(240±5) °C10secs	2 times	22	0/22

Criteria For Judging Damage

Test Items	Symbol	Test Conditions	Criteria For Judging Damage
Forward Voltage	V _F	I _F =I _{FT}	Initial Data±10%
Recease Current	I _R	V _R =5V	I _R ≤10uA
Luminous Intensity	I _V	I _F =I _{FT}	Average I _V degradation≤30% ; Single LED I _V degradation≤50%
Resistance to Soldering Heat			Material without internal cracks,no material between stripped,no dead light

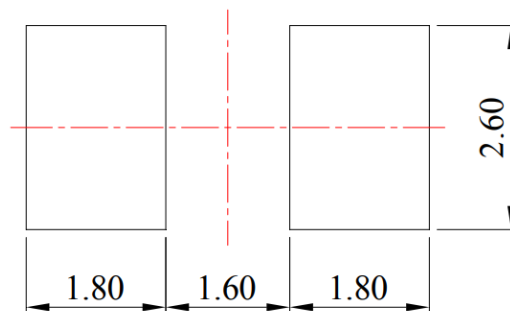
Product size (Unit:mm)



NOTES :

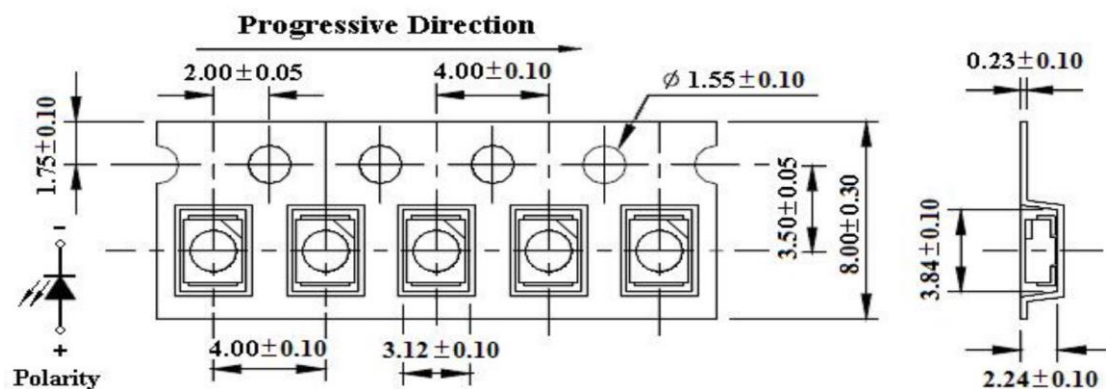
1. All dimensions are in millimeters (inches)
2. Tolerances are $\pm 0.2\text{mm}$ (0.008inch) unless otherwise noted

Recommended Soldering Pad Design (Unit:mm)

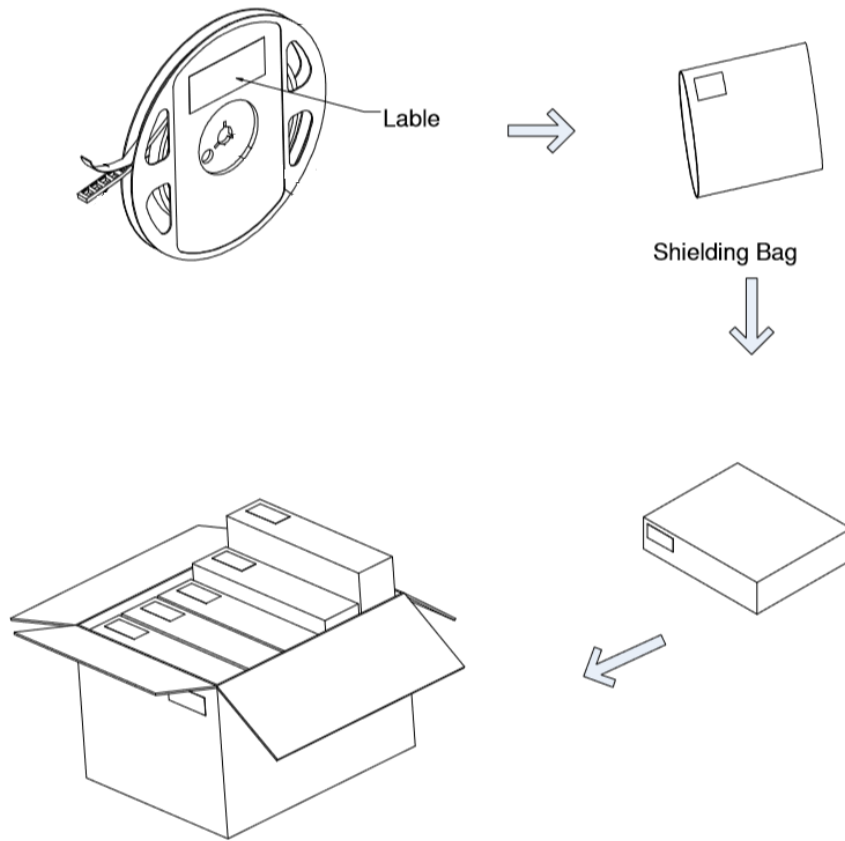


Taping and package Spec

- Tape Specification:2,000pcs Per Reel



Packaging



LabelStyle

MANUFACTURER


P/N:XXXXXXXXXXXXXXXXXX

Emitting Color: XXXX

HUE: XXX-XXX nm

IV : XXX-XXX mcd **example**

VF: XX-XX V

QTY: XX PCS

BIN Code: XX

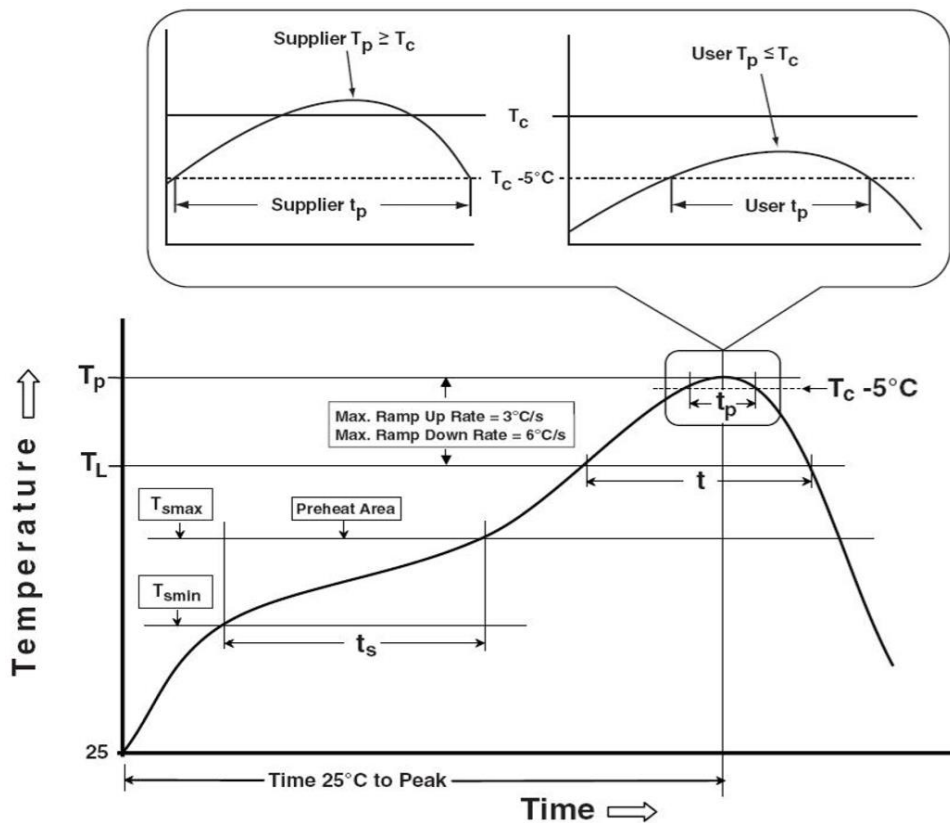
DATE: XXXX/XX/XX


LOT NO.:XXXXXXX

Table of Classification Reflow Profiles

Profile Feature	Sn Pb Eutectic Assembly	Pb Free Assembly
Preheat & Soak	100 °C	150 °C
Temperature min (T _{min})	150°C	200 °C
Temperature max (T _{max})	60 120 seconds	60 120 seconds
Time (T _{min} to T _{max}) (t _s)		
Average ramp up rate (T _{max} to T _p)	3 °C/second max	3 °C/second max
Liquidous temperature (T _L)	183 °C	217 °C
Time at liquidous (t _L)	60 150 seconds	60 150 seconds
Peak package body temperature (T _p)*	230 °C ~235 °C	255 °C ~260 °C
Classification temperature (T _c)	235 °C	260 °C
Time (t _p) within 5 °C of the specified Classification temperature (T _c)	20 seconds	30 seconds
Average ramp down rate (T _p to T _{max})	6 °C/second max	6 °C/second max
Time 25 °C to peak temperature	6 minutes max	8 minutes max

1. Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
2. Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.



Precautions

1. Storage:

- Moisture proof and anti electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.
- Before opening the package, the product should be kept at 30°C or less and humidity less than 60% RH, and be used within three months.
- After opening the package, the product should be stored at 30°C or less and humidity less than 10%RH, and be soldered within 24 hours (1day). It is recommended that the product be operated at the workshop condition of 30°C or less and humidity less than 60%RH.
- If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (70±5)°C for 24 hours.

2. Static Electricity:

Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristics such as the forward voltage becoming lower, or the LEDs do not light at the low current, even not light.

All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti electrostatic gloves, anti electrostatic containers be used when dealing with the LEDs.

3. Vulcanization:

LED curing is due to sulfur being in the bracket and the +1 price of silver in the chemical reaction generated Ag₂S in the process. It will lead to the capacity of reflecting of silver layer reducing, light color temperature drift and serious decline, seriously affecting the performance of the product. So we should take corresponding measures to avoid vulcanization, such as to avoid using sulphur volatile substances and keeping away from high sulphur content of the material.